



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Flangeless Termination 150 Watts, 50Ω



General Specifications

Resistive Element	Thick film
Substrate	Beryllium oxide ceramic
Cover	Alumina Ceramic
Lead(s):	99.9% pure silver (.006 thick)
Terminals	Thick film silver

Electrical Specifications

Resistance Range:	50 ohms, $\pm 5\%$
Frequency Range;	DC – 3.0 GHz
Power:	150 Watts
VSWR	1.10:1 DC – 1.0 GHz
	1.30:1 DC – 2.0 GHz
	1.40:1 DC – 3.0 GHz

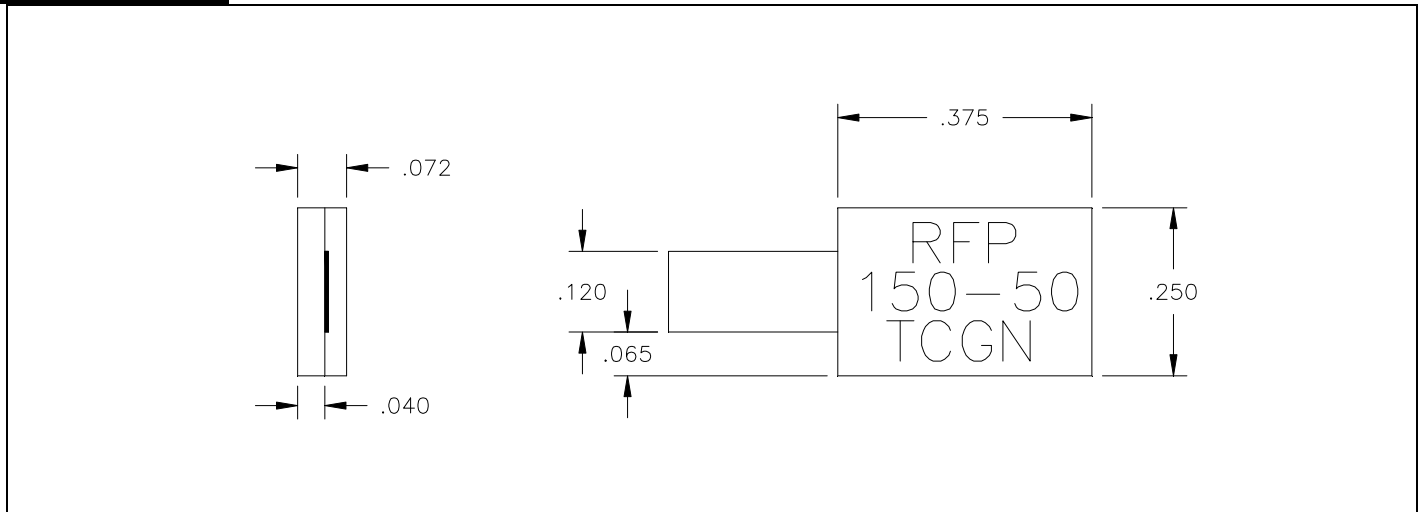
Note: Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is -55°C to 150°C (see chart for derating temperatures). All dimensions in inches.

Specifications subject to change with out notice.

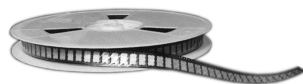
Features:

- DC – 3.0 GHz
- 150 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Outline Drawing

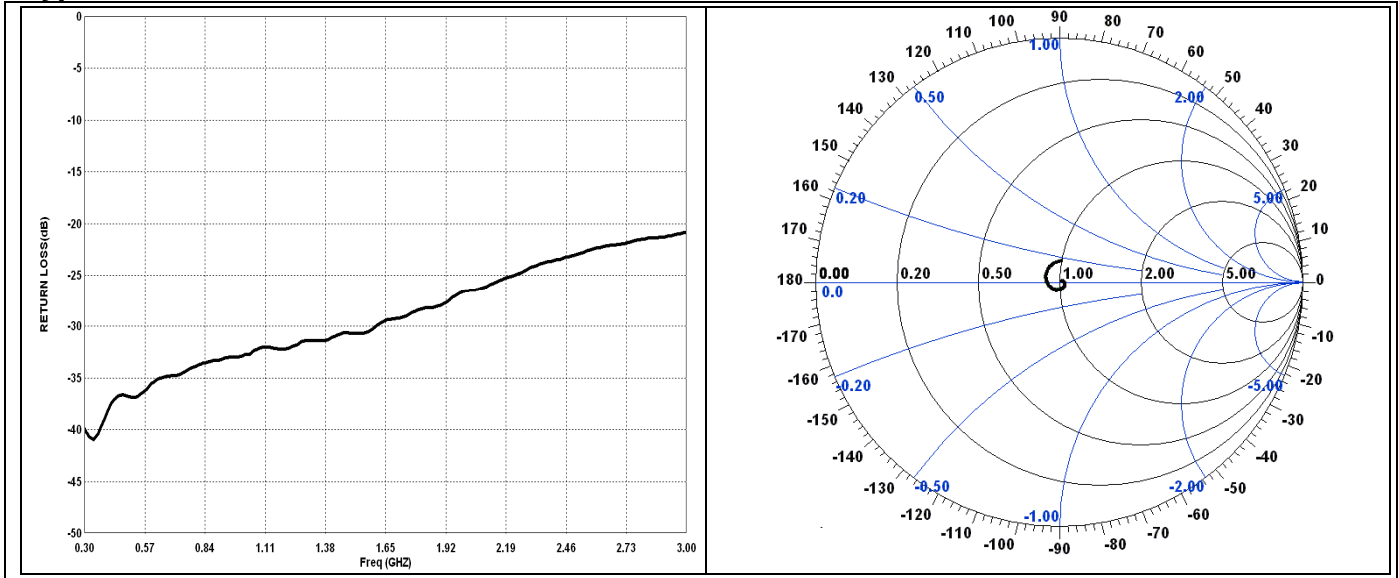


150-50TCGN (097) Rev A



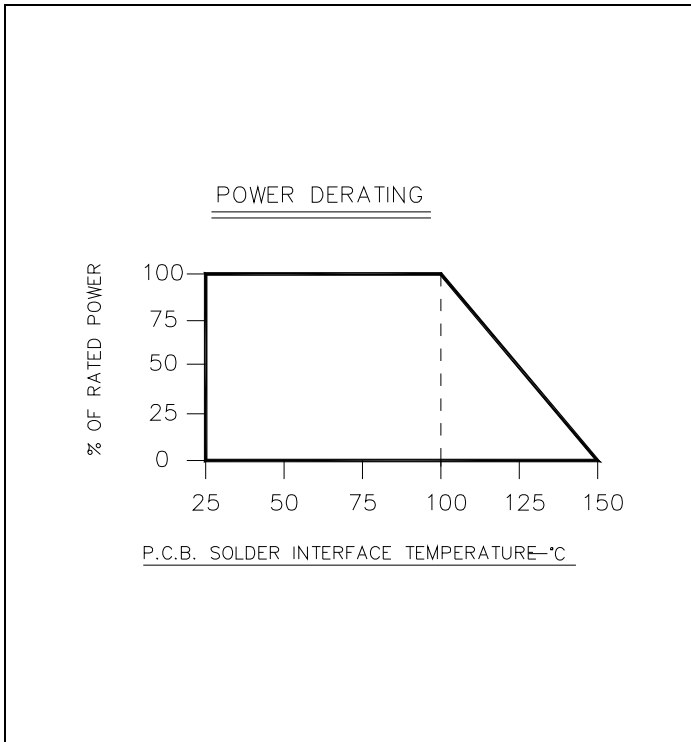


Typical Performance:



Power De-rating:

Mounting Footprint and Procedure:



Mounting Footprint and Procedure:

The diagrams show two methods for mounting the device. The left method, labeled 'SUGGESTED STRESS RELIEF METHODS', shows two cases: 'BOARD LOWER THAN LEAD' and 'BOARD EVEN WITH LEAD'. The right method, labeled 'NOT RECOMMENDED APPLICATION', shows two cases: 'BOARD LOWER THAN LEAD' and 'BOARD HIGHER THAN LEAD'. A dimension of .025 MIN. (2 PLACES) is indicated for the lead length. Scale: NONE.

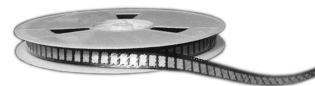
SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. POSITION DEVICE ON MOUNTING SURFACE AND SOLDER IN PLACE USING AN APPROPRIATE TYPE SOLDER.
3. SOLDER LEADS IN PLACE USING AN APPROPRIATE TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON. KEEP LEAD LENGTH AS SHORT AS POSSIBLE USING A SUGGESTED STRESS RELIEF METHOD.

150-50TCGN (097) Rev A

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Available on Tape and Reel For Pick and Place Manufacturing.



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